

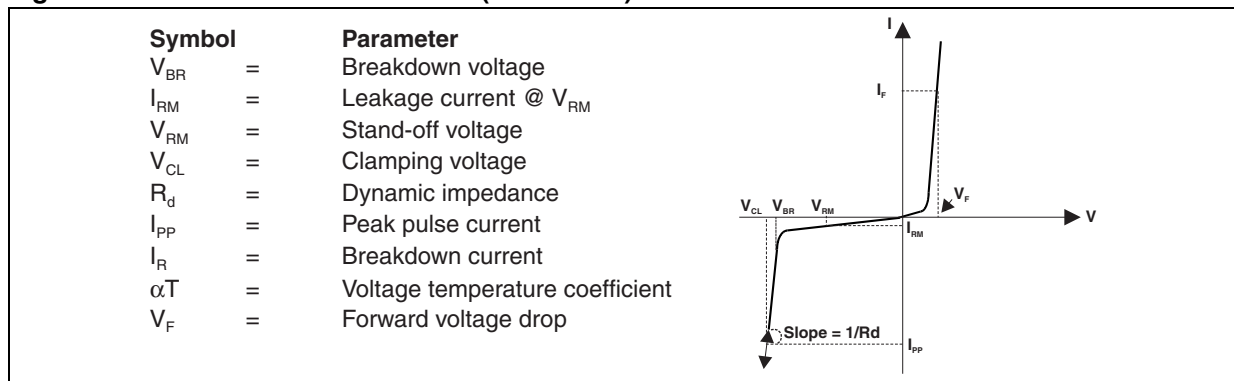
# 1 Characteristics

**Table 1. Absolute maximum ratings ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ )**

Symbol	Parameter	Value	Unit	
$V_{PP}$	Peak pulse voltage - IEC 61000-4-2	25	kV	
	Air discharge Contact discharge	20		
$P_{PP}$	Peak pulse power dissipation (8/20 $\mu\text{s}$ ) <sup>(1)</sup>	50	W	
$I_{PP}$	Peak pulse current (8/20 $\mu\text{s}$ ) <sup>(1)</sup>			$T_j \text{ initial} = T_{amb}$
$T_j$	Operating junction temperature range	- 40 to + 125	$^{\circ}\text{C}$	
$T_{stg}$	Storage temperature range	- 55 to +150	$^{\circ}\text{C}$	

1. For a surge greater than the maximum values, the diode will fail in short-circuit

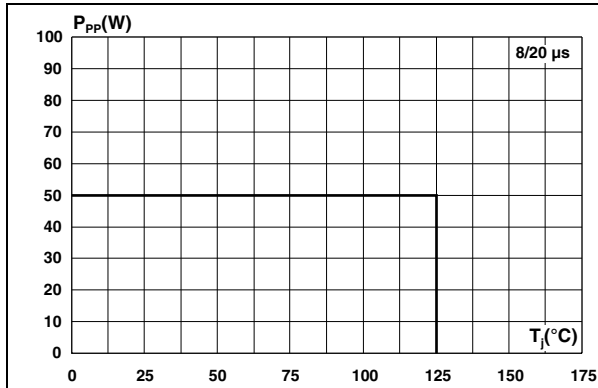
**Figure 2. Electrical characteristics (definitions)**



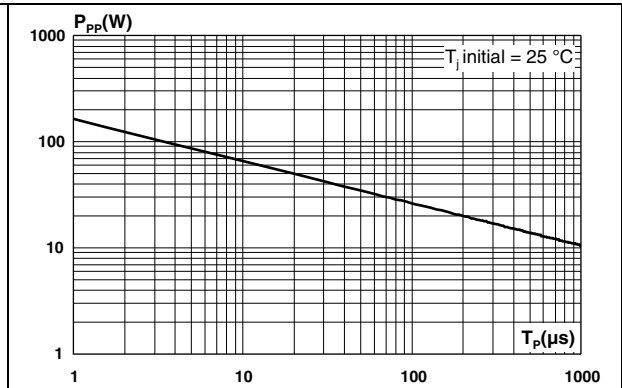
**Table 2. Electrical characteristics ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ )**

Symbol	Test conditions	Min.	Typ.	Max.	Unit
$V_{BR}$	$I_R = 1\text{ mA}$	12		14	V
$I_{RM}$	$V_{RM} = 10\text{ V}$			200	nA
$R_d$	1 A to 3 A, 8/20 $\mu\text{s}$		1.9		$\Omega$
$V_{CL}$	$I_{PP} = 1\text{ A}$ , 8/20 $\mu\text{s}$			20	V
C	$V_R = 0\text{ V DC}$ , $F = 1\text{ MHz}$ , $V_{OSC} = 30\text{ mV}_{RMS}$		15	18	pF

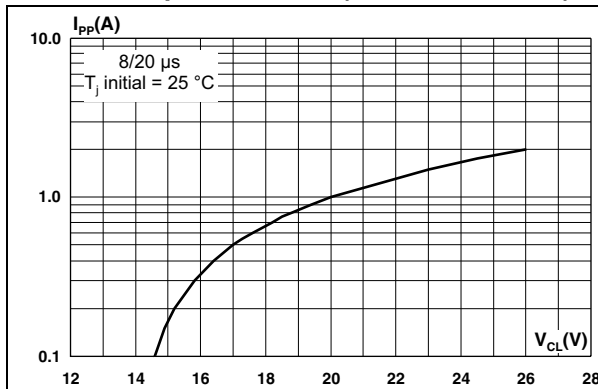
**Figure 3. Peak pulse power dissipation versus initial junction temperature**



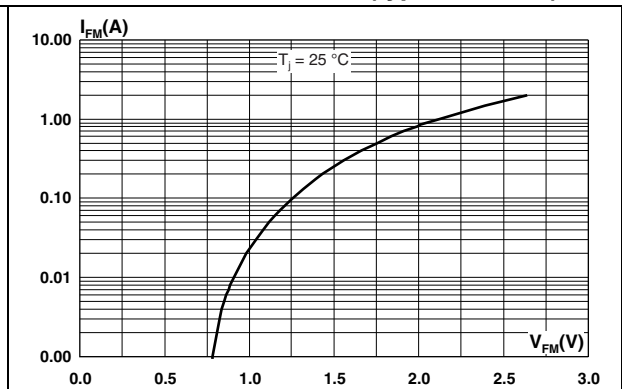
**Figure 4. Peak pulse power versus exponential pulse duration**



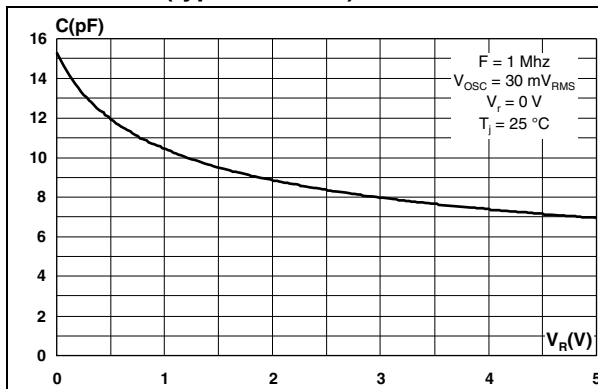
**Figure 5. Clamping voltage versus peak pulse current (maximum values)**



**Figure 6. Forward voltage drop versus peak forward current (typical values)**



**Figure 7. Junction capacitance versus reverse applied voltage (typical values)**



**Figure 8. Leakage current versus junction temperature (typical values)**

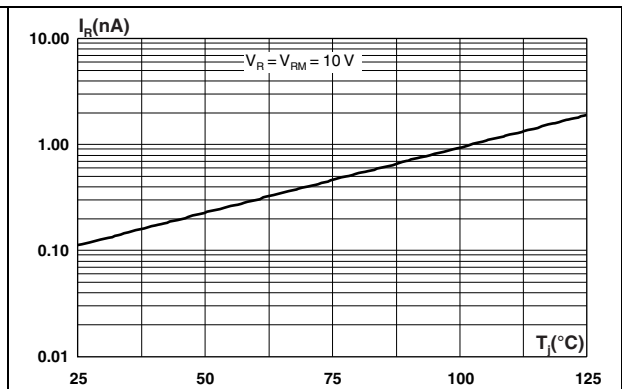


Figure 9. ESD response to IEC 61000-4-2 (+15 kV air discharge) on each channel

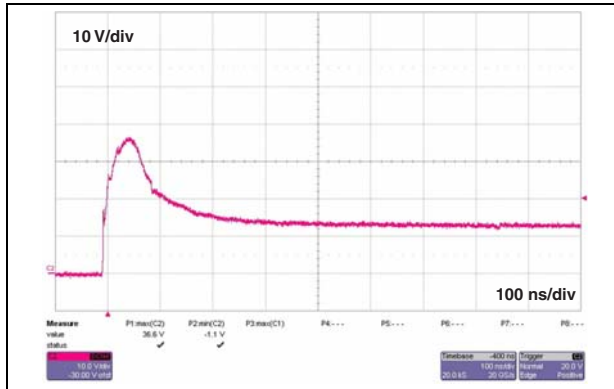


Figure 10. ESD response to IEC 61000-4-2 (-15 kV air discharge) on each channel

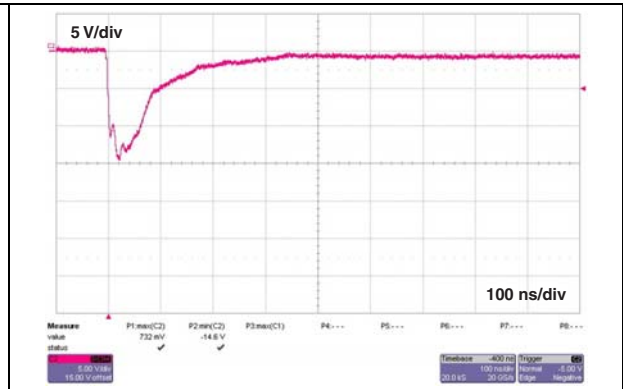
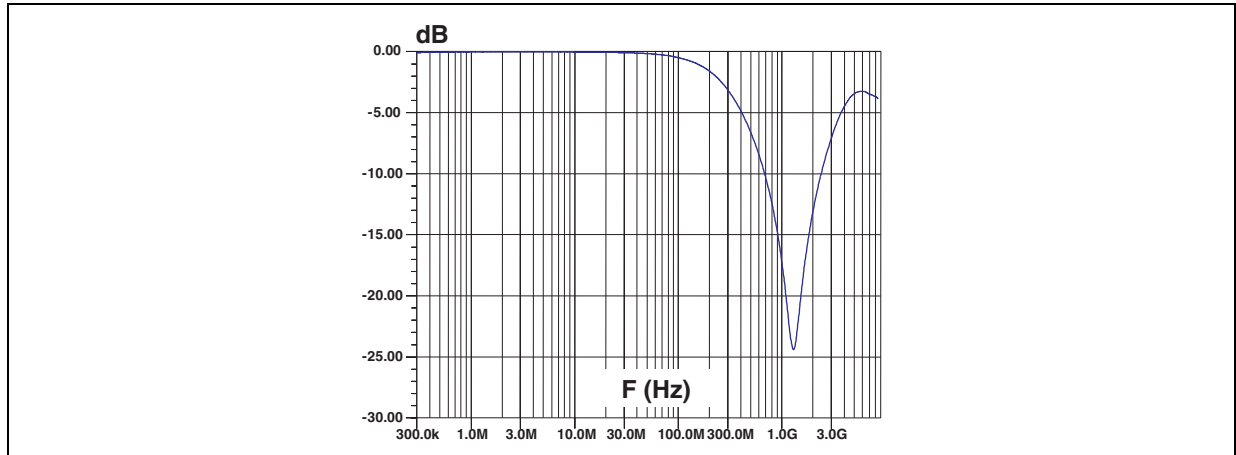
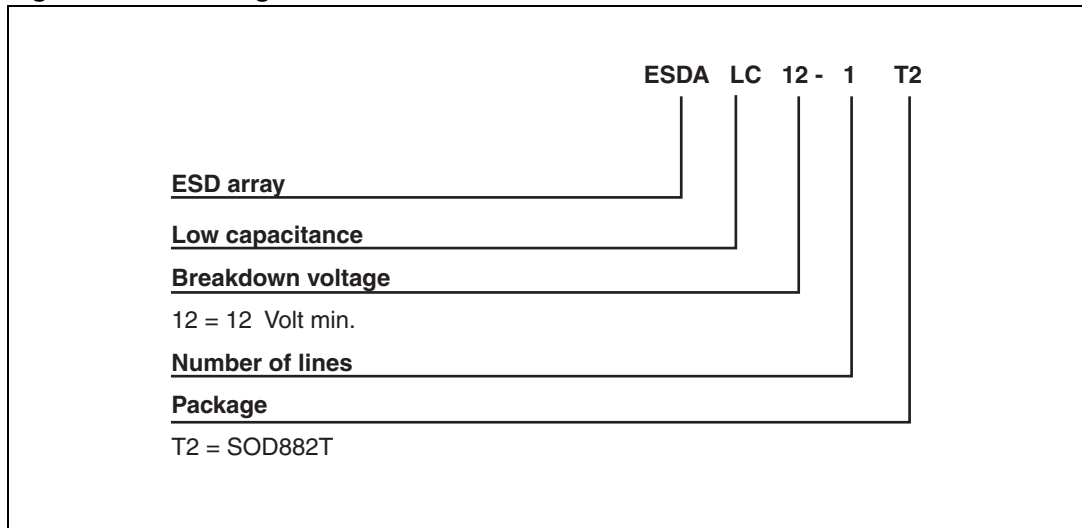


Figure 11. S21 attenuation measurement



## 2 Ordering information scheme

Figure 12. Ordering information scheme

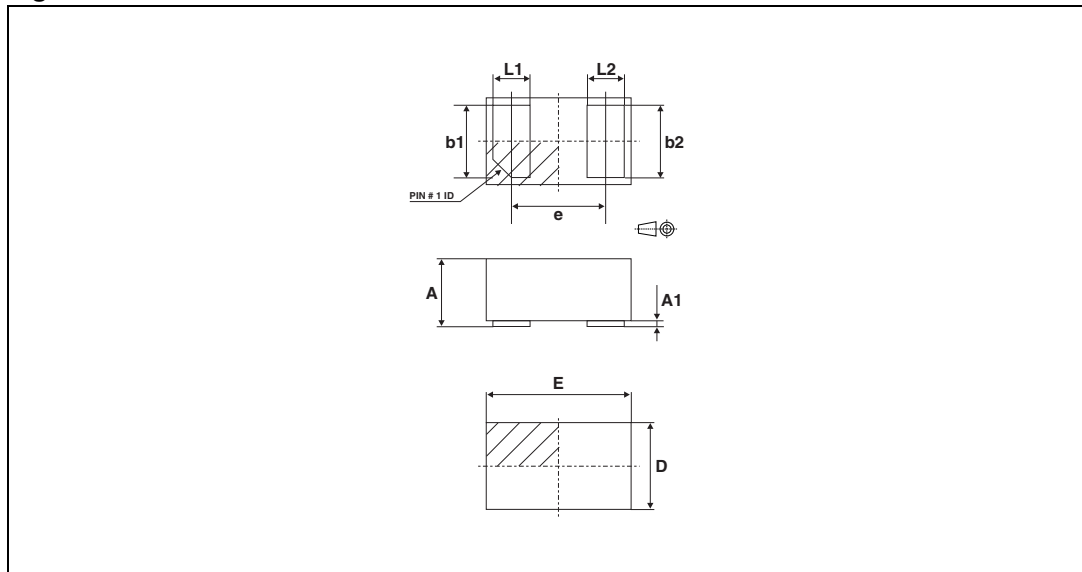


### 3 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

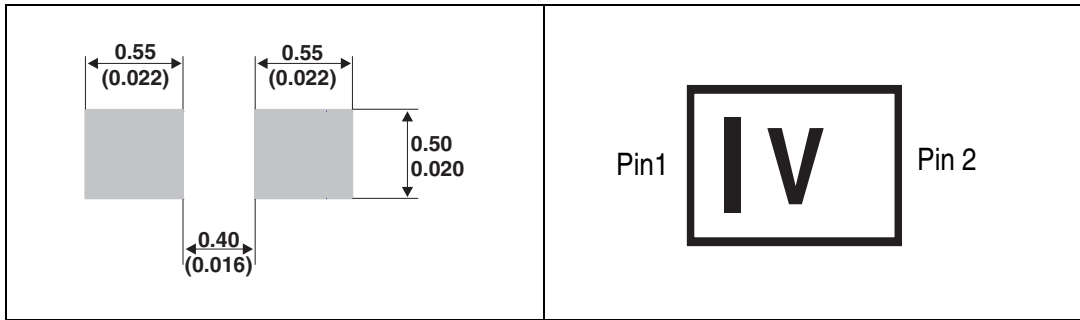
**Figure 13. SOD882 dimension definitions**



**Table 3. SOD882 dimension values**

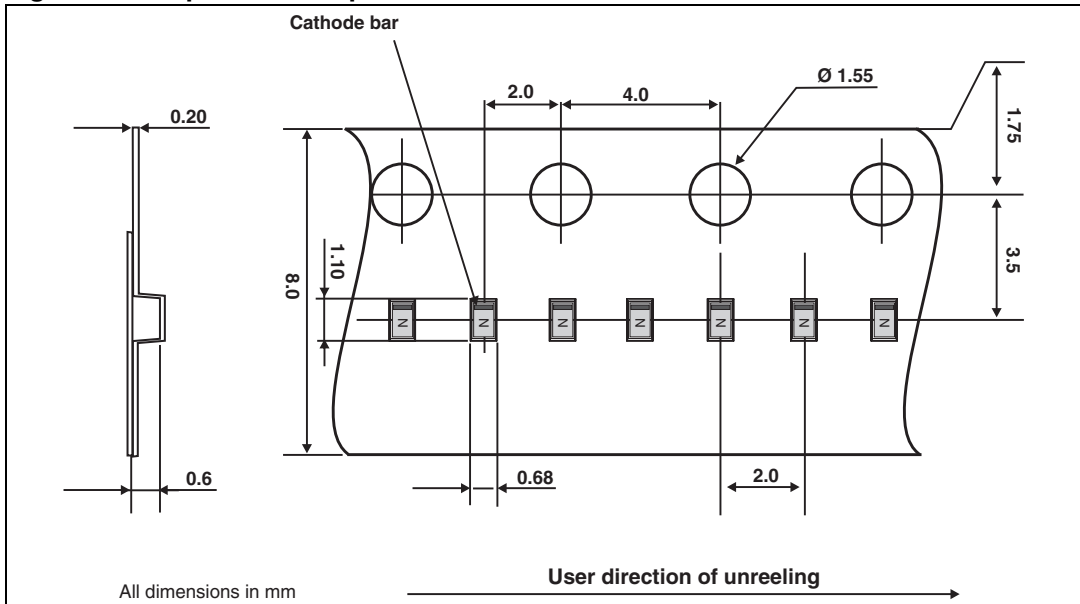
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.47	0.50	0.016	0.019	0.020
A1	0.00		0.05	0.000		0.002
b1	0.45	0.50	0.55	0.018	0.020	0.022
b2	0.45	0.50	0.55	0.018	0.020	0.022
D	0.55	0.60	0.65	0.022	0.024	0.026
E	0.95	1.00	1.05	0.037	0.039	0.041
e	0.60	0.65	0.70	0.024	0.026	0.028
L1	0.20	0.25	0.30	0.008	0.010	0.012
L2	0.20	0.25	0.30	0.008	0.010	0.012

Figure 14. Footprint (dimensions in mm) Figure 15. Marking



Note: Product marking may be rotated by multiples of 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

Figure 16. Tape and reel specifications

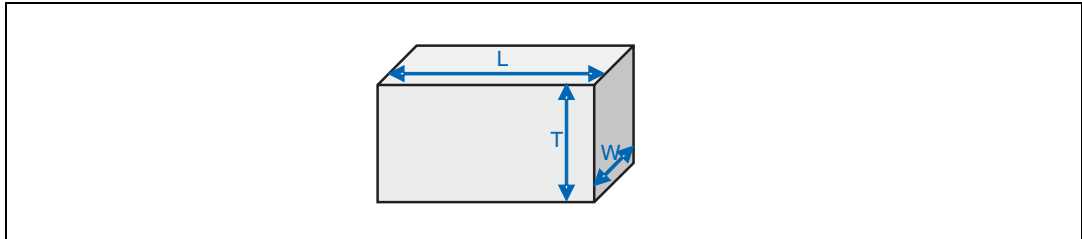


## 4 Recommendation on PCB assembly

### 4.1 Stencil opening design

1. General recommendation on stencil opening design
  - a) Stencil opening dimensions: L (Length), W (Width), T (Thickness).

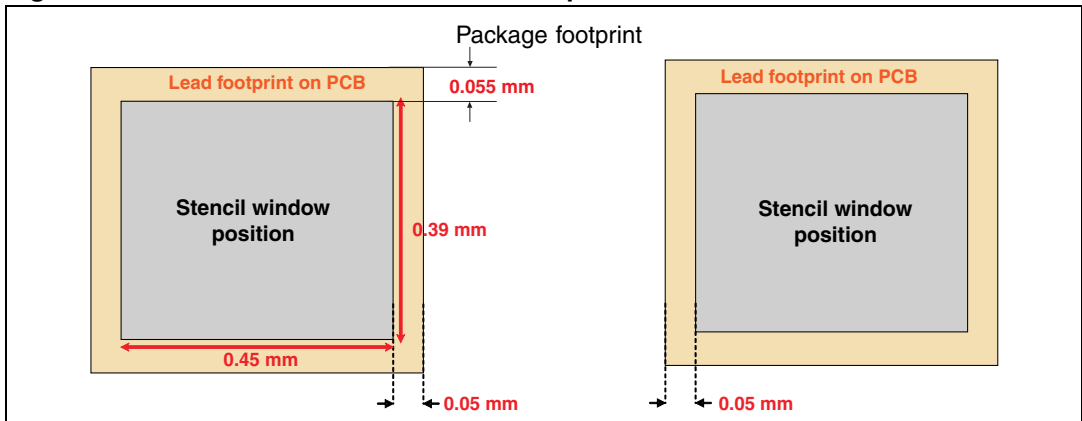
**Figure 17. Stencil opening dimensions**



- b) General design rule
  - Stencil thickness (T) = 75 ~ 125 μm
  - Aspect Ratio =  $\frac{W}{T} \geq 1.5$
  - Aspect Area =  $\frac{L \times W}{2T(L + W)} \geq 0.66$

2. Reference design
  - a) Stencil opening thickness: 100 μm
  - b) Stencil opening for leads: Opening to footprint ratio - between 60% and 65%.

**Figure 18. Recommended stencil windows position**



### 4.2 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. “No clean” solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed
4. Solder paste with fine particles: powder particle size is 20-45 μm.

### 4.3 Placement

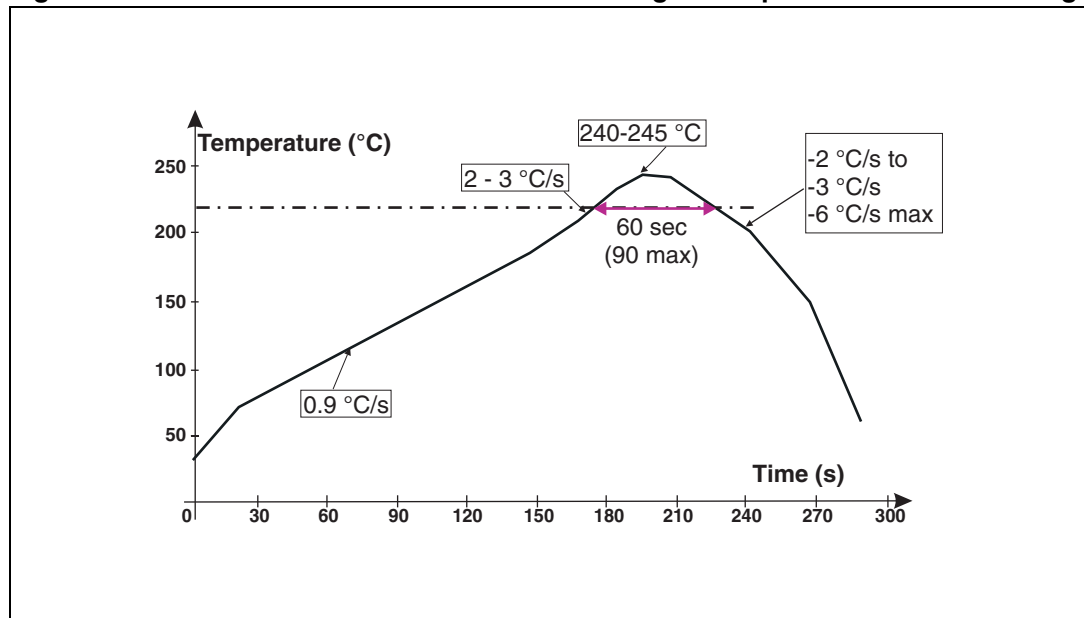
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
3. Standard tolerance of  $\pm 0.05$  mm is recommended.
4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

### 4.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

### 4.5 Reflow profile

Figure 19. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.



## 5 Ordering information

**Table 4. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDALC12-1T2	V <sup>(1)</sup>	SOD882T	0.76 mg	12000	Tape and reel

1. The marking can be rotated by multiples of 90° to differentiate assembly location

## 6 Revision history

**Table 5. Document revision history**

Date	Revision	Changes
16-Sep-2008	1	Initial release
02-Nov-2010	2	Updated <a href="#">Table 1</a> , base quantity change on <a href="#">Table 4</a> and updated graphics.
13-Jun-2012	3	Added <a href="#">Figure 13</a> , updated <a href="#">Table 3</a> and added note after <a href="#">Figure 15</a> .

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